

Title of Invention

BONDING APPARATUS AND BONDING METHOD

ABSTRACT

There are provided an intermediate stage 41; a transfer unit 30 configured to transfer a semiconductor chip 11 and to place the semiconductor chip 11 on the intermediate stage 41; and a first bonding unit 50A and a second bonding unit 50B each configured to pick up the semiconductor chip 11 from the intermediate stage 41, and to bond the semiconductor chip 11 to a circuit substrate 15. The intermediate stage 41 moves between a first position P1 and a second position P2. The first position P1 is a position at which the first bonding unit 50A is allowed to pick up the semiconductor chip 11, and the second position P2 is a position at which the second bonding unit 50B is allowed to pick up the semiconductor chip 11. With this, it is possible to provide a bonding apparatus capable of reducing processing time per circuit substrate and suppressing an increase of a space, as well as such a bonding method.

FIGURE 1